

**AMENDMENTS TO THE ABSTRACT**

Please amend the Abstract as follows:

~~The present invention discloses a~~A light emitting device package, comprising:includes a metal ~~base~~base, an electrical circuit layer provided at an upper side of the metal base for providing a conductive ~~path~~path, a light emitting device mounted in a second region having a smaller thickness than a first region on the metal ~~base~~base, an insulating layer sandwiched between the ~~meta~~metal base and the electrical circuit ~~layer~~layer, an electrode layer provided at an upper side of the electrical circuit ~~layer~~layer, and a wire for electrically connecting the electrode layer and the light emitting device. ~~Further, there is provided a~~The light emitting device package ~~which is improved in~~has improved light emission efficiency since the light emitting device is placed on a small thickness portion of the metal base.